| ASSOCIATION CONNECTING<br>ELECTROMICS INDUSTRIES* | PC. Bannockl   | burn, Illinois, A                | Il rights reserved ntions. | under both          | This docum<br>level parts, t  | ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities are an entities and the declaration entities are an entities and the declaration entities are an entite are an entities are an entities are an entite are | on of the su<br>compasses       | bstances v<br>s all lower | vithin the manufactu<br>level materials for w | rer listed<br>which the 1       | item. Note<br>nanufactur        | : if the item is an as<br>er has engineering | sembly with low responsibility. |  |
|---|--|----------------------------------|----------------------------|---------------------|---|---|---------------------------------|---------------------------|---|---------------------------------|---------------------------------|--|---------------------------------|--|
|   | -21.1 IPC Web Site for Information on IPC-1752 Standard For<br>http://www.ipc.org/IPC-175x Dis |                                  |                            |                     | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials and M |   |                                 |                           | lfg Inform                                    | ation                           |                                 |  |                                 |  |
| Supplier Information                              |  |                                  |                            |                     |   |   |                                 |                           |   |                                 |                                 |  |                                 |  |
| Company name* Compa                               |  |                                  | ompany unique ID           |                     |   | Unique ID Authority   |                                 |                           |   | Respon                          | Response Date*                  |  |                                 |  |
| nsemi   |  |                                  |                            |                     |   |   |                                 |                           |   |                                 | 2024-04-20                      |  |                                 |  |
| ntact Name Title - Contact                        |  |                                  | et                         |                     | Phone - Contac  | hone - Contact*   |                                 |                           | Email - Contact*                              |                                 |                                 |  |                                 |  |
| Product-Env-Stewards Product Enviro               |  |                                  | iro Compliance             |                     |   | NA  |                                 |                           |   | Product-Env-Stewards@onsemi.com |                                 |  |                                 |  |
| Authorized Representative* Title - Represen       |  |                                  | entative                   |                     | Phone - Representative*   |   |                                 | Email - Representative*   |   |                                 |                                 |  |                                 |  |
| Product-Env-Stewards Product Env                  |  |                                  | Enviro Compliance          |                     |   | NA  |                                 |                           |   | Produ                           | Product-Env-Stewards@onsemi.com |  |                                 |  |
| Requester Item Number                             | Mfr Iten   | n Number                         | Mfr Item Name              |                     |   | Effective Date  | Date Version Manufacturing Site |                           | Ianufacturing Site                            |                                 | Weight*                         | UOM  | Unit Type                       |  |
|   | MAX80<br>G   | MAX809SQ293D3T1 ANA 2.93V N<br>G |                            | MCROPROC RESET      |   | 2024-04-20  |                                 | М                         | MY1   |                                 | 6.0                             | mg   | Each                            |  |
| Aanufacturing Proccess Informat                   | tion   |                                  |                            |                     |   |   |                                 |                           |   |                                 |                                 |  |                                 |  |
| Terminal Plating / Grid Array Ma                  | terial   | Ferminal Base A                  | Alloy                      | J-STD-020 MSL Ratin |   | Peak Process Body Temperate   |                                 | emperature                | ure Max Time at Peak Temper                   |                                 | ture Nur                        | nber of Reflow Cyc                           | les                             |  |
| Matte Tin (Sn) - annealed CU Alloy                |  | CU Alloy                         |                            | 1                   |   | 260   |                                 | С                         | 30  | seco                            | nds 3                           |  |                                 |  |
| omments   |  |                                  |                            |                     |   |   |                                 |                           |   |                                 |                                 |  |                                 |  |
| vel 1 - maximum time at peak temperatu            | re during so   | dering is 10-3                   | 0 seconds                  |                     |   |   |                                 |                           |   |                                 |                                 |  |                                 |  |
| or more information regarding material            | composition  | please refer to                  | page 3                     |                     |   |   |                                 |                           |   |                                 |                                 |  |                                 |  |

| RoHS Material Composition Declaration  |  |   |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|--|---|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | (Pb), Mercury (Hg), Hexavalent Chror   | IS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead , Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl alate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies  | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | on above  | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above  | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |   |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |   |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th   | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le  |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance                  | CAS              | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|----------------------------|------------------|--------|--------|-----------------|
| Die                  | 0.1    | mg              | Supplier | Silicon (Si)               | 7440-21-3        |        | 0.1    | mg              |
| Die Attach           | 0.15   | mg              | Supplier | Silver (Ag)                | 7440-22-4        |        | 0.1125 | mg              |
|                      |        |                 | Supplier | Epoxy resins               | 129915-35-1      |        | 0.0375 | mg              |
| Lead Frame           | 1.93   | mg              | В        | Nickel (Ni)                | 7440-02-0        |        | 0.7392 | mg              |
|                      |        |                 | Supplier | Iron (Fe)                  | 7439-89-6        |        | 1.021  | mg              |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8        |        | 0.1698 | mg              |
| Mold Compound-Black  | 3.7    | mg              |          | Epoxy resin                | proprietary data |        | 0.185  | mg              |
|                      |        |                 |          | Phenolic Resin             | Proprietary Data |        | 0.185  | mg              |
|                      |        |                 | Supplier | Ortho Cresol Novolac Resin | 29690-82-2       |        | 0.074  | mg              |
|                      |        |                 | Supplier | Carbon Black (C)           | 1333-86-4        |        | 0.0185 | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0       |        | 3.2375 | mg              |
| Plating              | 0.11   | mg              | Supplier | Tin (Sn)                   | 7440-31-5        |        | 0.11   | mg              |
| Wire Bond - Au       | 0.01   | mg              | Supplier | Gold (Au)                  | 7440-57-5        |        | 0.01   | mg              |